

PRODUCT SPECIFICATION PCI Express 1.0 Pitch Connectors Series	SPEC.No.: PCI-1.0	
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1. SCOPE:

1.1. CONTENTS

This specification covers the performance, tests and quality requirements for the **PCI Express 1.0 Pitch Connectors Series.**

1.2. QUALIFICATION

When tests are performed on the subject product line, the procedures specified in Kemax specifications shall be used. All inspections shall be performed using the applicable inspection plan and product drawing.

2. APPLICABLE DOCUMENT

The following documents form a part of this specification to the extent specified herein. Unless otherwise specified, the latest edition of the document applies. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

3. REQUIREMENTS

3.1. DESIGN AND CONSTRUCTION

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2. MATERIALS

A. Housing : Thermoplastic or Thermoplastic High Temp., UL94V-0

B. Contact :Copper Alloy, Gold plating on contact area, Tin Plating on soldertail over Nickel under plating overall. Tin Plating on Clip over Nickel under plating overall.

3.3. RATINGS

A. Voltage: **50** VAC rms.

B. Current: 1.1 A Max

C. Temperature: - **40**°C to **85** °C

4. ACCMMODATED CABLE AND P.C.Board

4.1 Thickness:0.8(.031") ~1.6mm(.063")

4.2 P.C.Board Layout:See attaced drawings

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5.PRODUCT PERFORMANCE AND REQUIREMENTS:

Electrical Performance		
Test Description	Test Procedures & Condition	Requirements
Contact Resistance	Subject mated contacts assembled in housing to 20mV Max open circuit at 10mA Max. EIA-364-23. Refer to Fig.3	[30] m Ohm Max. (Initial) [40] m Ohm Max. (Final)
Insulation Resistance	After [500] V DC for 1 minute, measure the insulation resistance between the adjacent contacts of unmated connector assemblies. EIA-364-21.	[1000] M Ohm Min.
Dielectric Withstanding Voltage	[500] VAC for 1minute Test between adjacent circuits of unmated connector. EIA-364-20C	No creeping discharge or flashover shall occur. Current leakage: 0.5 mA MAX

Mechanical equirement		
Test Description	Test Procedures & Condition	Requirements
Connector Mating Force	Operation Speed : [12.5] mm/min. Measure the force required to mate connector. EIA-364-13	117g (1.15N)/Per pin Max.for 1.7t gauge.
Connector Unmating Force	Operation Speed : [12.5] mm/min. Measure the force required to unmate connector. EIA-364-13	15.3g (0.15N)/Per pin Min.for 1.44t gauge
Durability	Connector shall be subjected to 20 cycles of Insertion and withdrawa	ontact resistance:Less than twice of initial
Contact Retention Force	Measure the contact retention force with Tensile strength tester.	0.5 kgf /per pin Min.
Solder ability	Steam Aging Preconditioning : 93+3/-5℃ 、100%HR 、8hrs. <J-STD-002 category 3 aging> Solder pot temperature: 245±5℃, 5sec	The inspected area of each lead must have 95% solder coverage minimum.

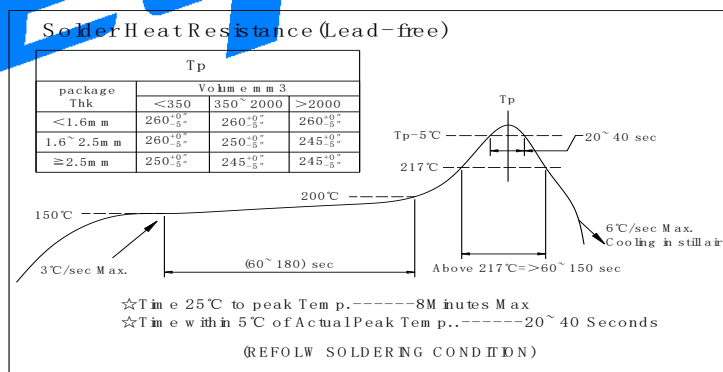
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Environmental Performance		
Test Description	Test Procedures & Condition	Requirements
Resistance to Wave Soldering Heat	Solder Temp. : 245°C , 10±0.5sec.	No physical damage shall occur.
Salt Spray	EI Subject mated connectors to 35±2 °C and 5±1% salt condition for 48hours . After test, rinse the sample with water and recondition the room temperature for 1 hour. EIA-364-26B.	No detrimental corrosion allowed in contact area and base metal exposed
Examination of Product	Visual inspection.	Meets requirements of product drawing. No physical damage.

Soldering Condition:

Reflow soldering

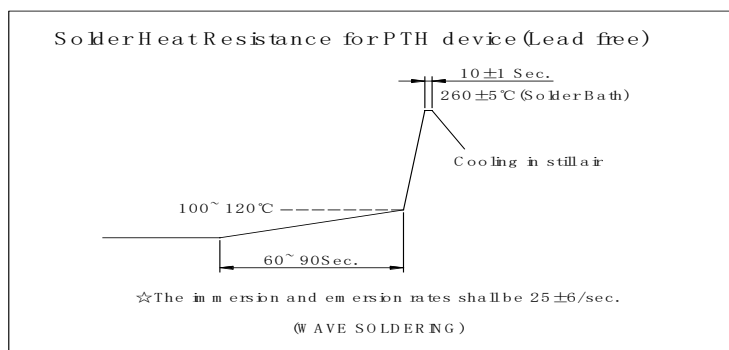
Lead-Free-PC / PC-STD-020C



Wave Soldering

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Lead-Free-JESD 22-B 106C-Lead-free



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